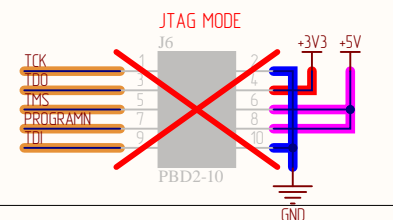
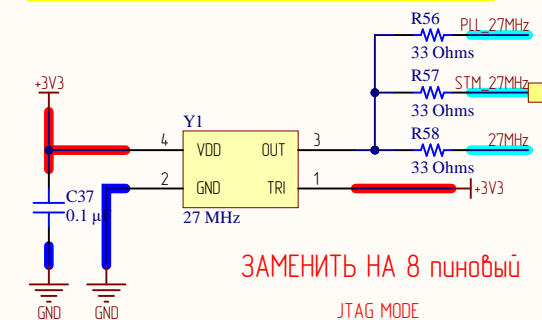
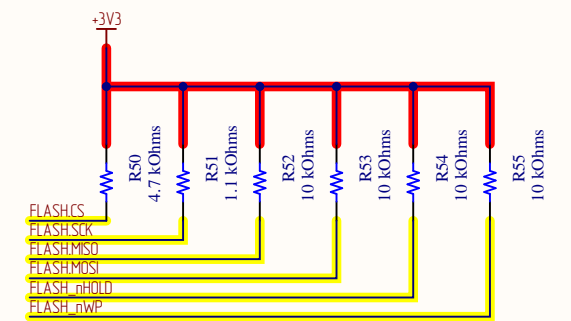
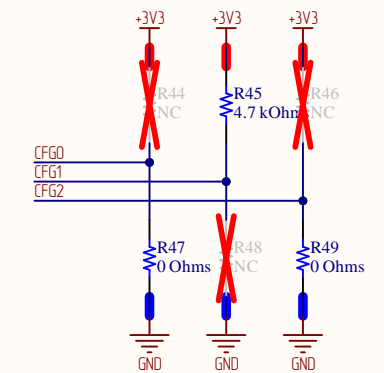
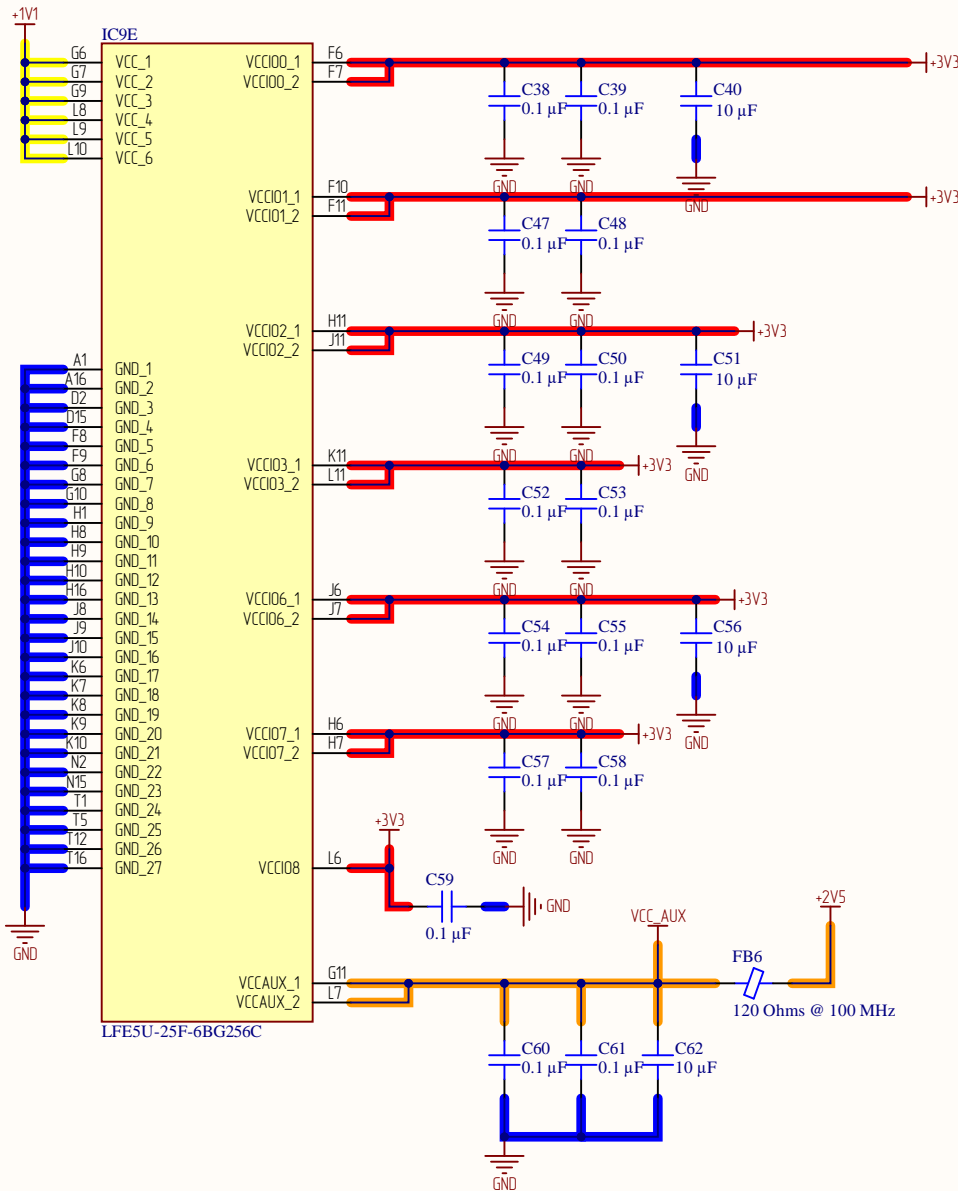
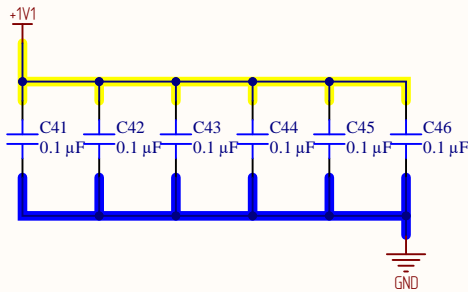


Configuration Mode	Bus Size	Dedicated CFG[2:0]	Clock		Shared Pins	Dedicated Pins
			CLK	I/O		
SSPI	1 Bit	001	PIN	Input	MISO, MOSI, S1, DOUT,	PROGRAMM, INITN, DONE
MSP ²	1 Bit	010	MCLK	Output	MISO, MOSI, CSSIPN, DOUT	PROGRAMM, INITN, DONE
	2 Bits				D[1:0], CSSIPN, DOUT	
	4 Bits				D[3:0], CSSIPN, DOUT	
SCM	1 Bit	101	CLK	Input	D ₀ , DOUT	PROGRAMM, INITN, DONE
SPCM (Parallel)	8 Bits	111	CLK	Input	D[7:0], DOUT, CS0N, BUSY ³ , WRITEN, CS1 _N , CS1 _N	PROGRAMM, INITN, DONE
JTAG	1 Bit	xxx	TCK	Input	—	TCK, TMS, TDI, TDO

- Notes:**
1. SN should have 4.7 k Ω pull-up resistor on-board for SSPI.
 2. CSSIPIN should have 4.7 k Ω pull-up on-board resistor for MSPI.
 3. D[7:0] should have 10 k Ω pull-up resistor on-board for SPCM.
 4. MOSI and MISO should have 10 k Ω pull-up resistor on-board for MSPI.
 5. IO[3:2] should have 10 k Ω pull-up resistor on-board for QUAD MSPI.
 6. MCLK should have a 1 k Ω pull-up. See Figure 6.1.





Title		
Size	Number	Revision
A3		
Date:	9.05.2025	Sheet of
File:	C:\Documents\...\FPGA_POWER.SchDoc	Drawn By:

A

B

C

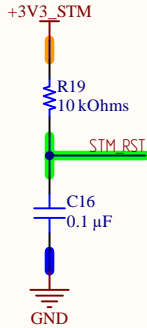
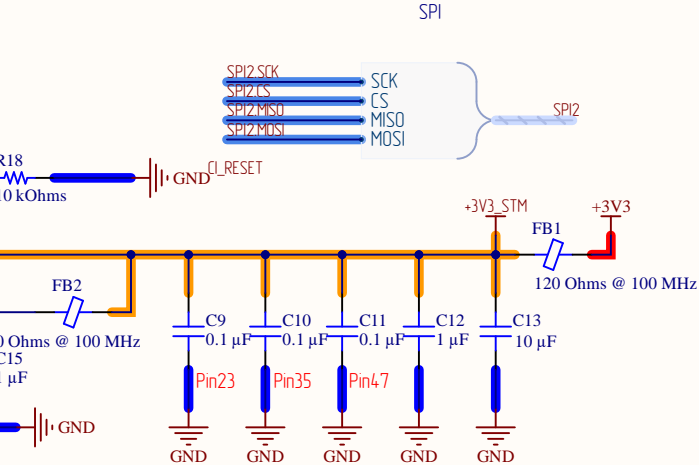
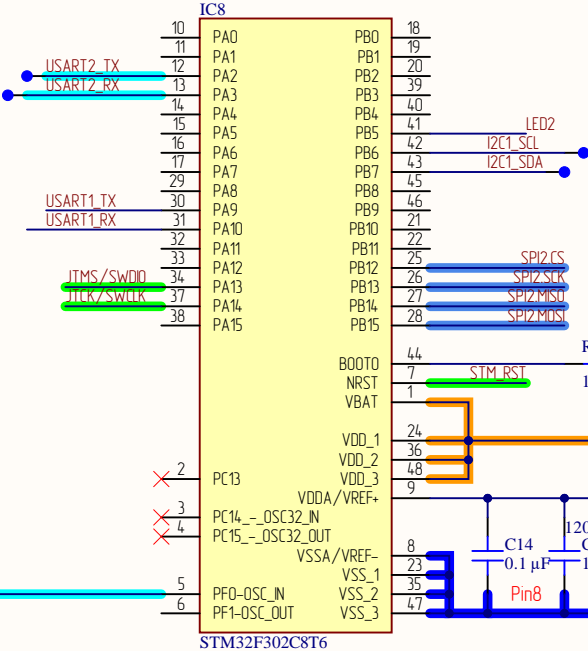
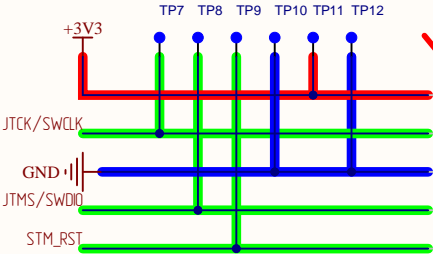
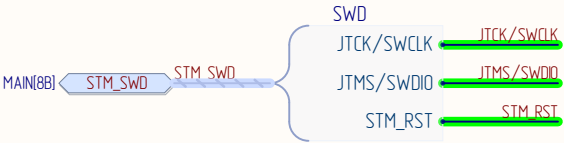
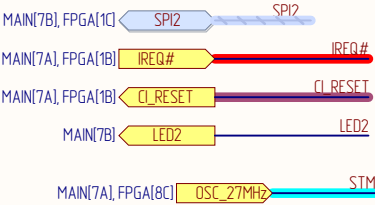
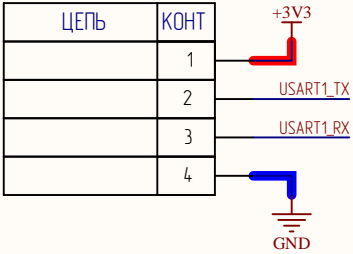
D

A

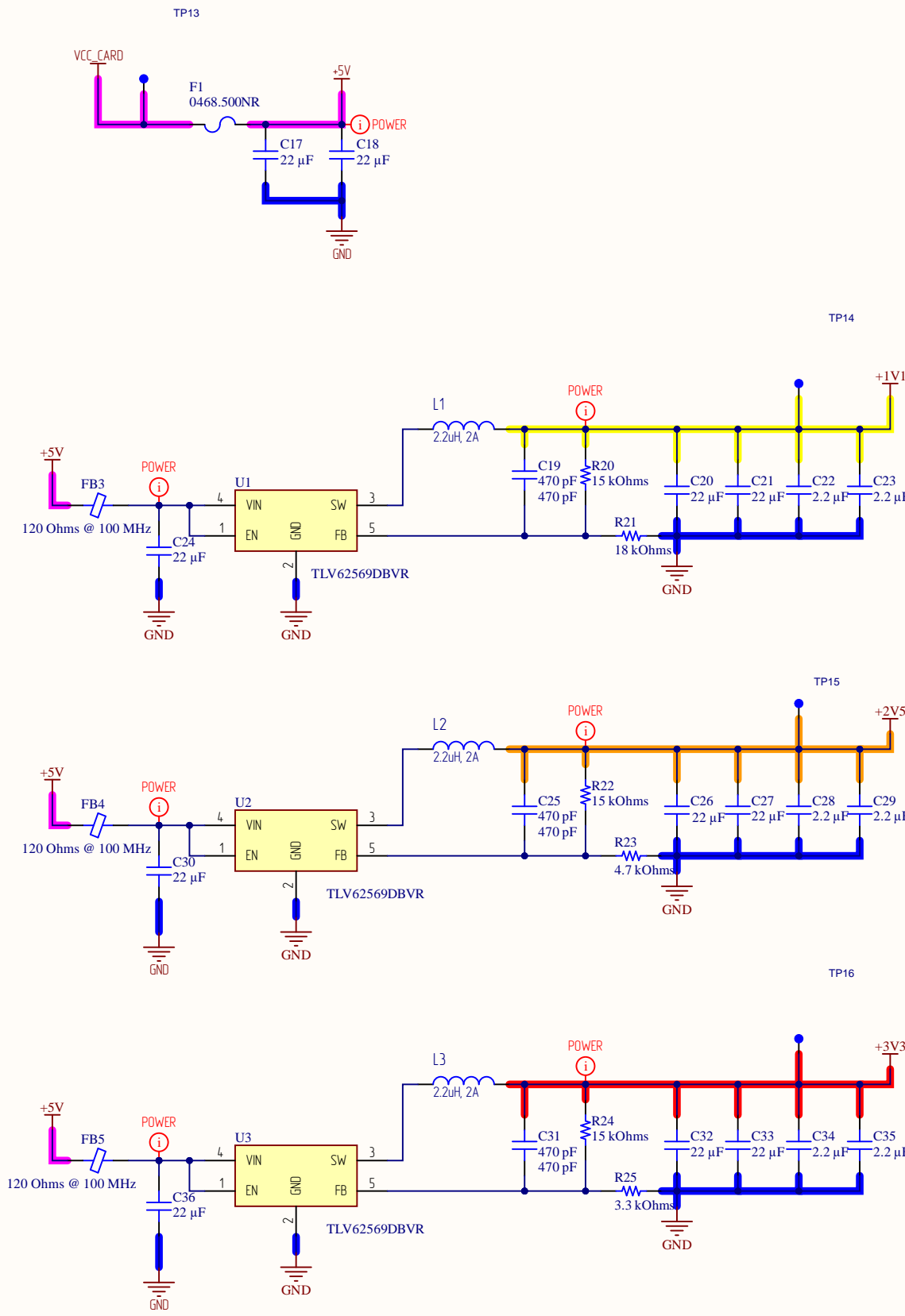
B

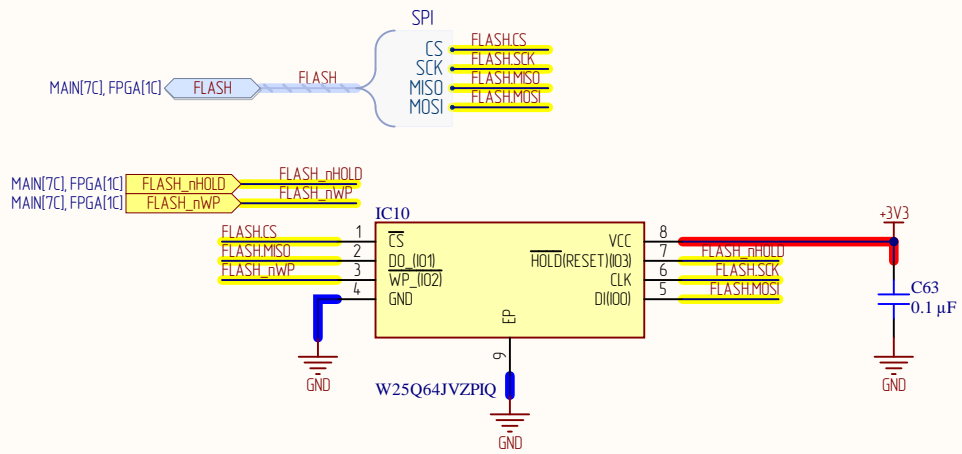
C

D



Title		
Size	Number	Revision
A4		
Date	9.05.2025	Sheet of
File	C:\Documents\...\STM32.SchDoc	Drawn By:





Title		
Size A4	Number	Revision
Date 9.05.2025	Sheet of	
File C:\Documents\...\FLASH.SchDoc	Drawn By:	

rev.1 first release
rev.1.1 SCHEMATIC

signal BUS_OE to U1 pin 83 (R30, R31, R33, R34, R35 убраны)
пины ПЛИС 94, 96, 97 убраны DNP резисторы, 0 Ohm подключены к GND напрямую
убраны разъемы J2 (программирования флэш), J4 (AS mode ПЛИС)
R8 корректно подключен с пина 4 IC2 на GND (был на VCC)
RN1 – RN12 заменены с 330 Ом на 33 Ома
R6, R7 убраны (поддержка STM32F1 отсутствует)
LED1 переключен на ПЛИС
X1 -> заменен на J2 -> заменен на PBS2-6
VPP и VCC разделены. Пины 18 и 52 (VPP) отключены от шины питания VCC.

rev.20	Lattice FP caBGA256	recommend	0.45	0.53		
		example	0.35	0.5	0.100/0.100	0.4/0.15
		current	0.42	0.54	0.125/0.125	0.4/0.2

PCB
PCB сжать до 50*75
корректное подключение полигона 3V3 рядом с DCDC
STACKUP Total 0.86mm
Copper 1oz
IMPEDANCE Width 0.15mm - S75 - Imp 68.2(-9%) Standart = 60-90 Ohm
ADD "POWER" class with VIA 0.6/0.3

rev.1.11 STM_RCC_OUT удържан с ПЛИС и СТМ, на 5 OSC_IN заеден сигнал с генератора у3

TODO разобраться с питанием ПЛИС, лишние домены с DSCD убрать

Title		
Size A4	Number	Revision
Date:	9.05.2025	Sheet of
File:	C:\Documents\...\INFO.SchDoc	Drawn By: